

WHAT IS CLAIMED IS:

1. An electronic unit comprising:

a module in which a semiconductor device is attached on
5 the bottom of a circuit board and which has lands provided on
the bottom of the circuit board with the lands being
connected to the semiconductor device; and

a printed circuit board on which the module is mounted,
the printed circuit board having a hole in a position
10 facing the semiconductor device and having electrical
conductors to which the lands are soldered,

wherein the module is mounted on the printed circuit
board by soldering the lands to the electrical conductors
while the semiconductor device is disposed in the hole.

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2. An electronic unit according to Claim 1, wherein
solder balls are applied on the lands, and the lands and the
electric conductors are soldered together with the solder
balls.

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3. An electronic unit according to Claim 2, wherein the
wall of the hole has recesses that receive the corresponding
solder balls and have electrical conductors applied to the
walls of the recesses.